

1            ABSTRACT OF THE DISCLOSURE UNDER 37 C.F.R. §1.72(b)  
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3            Selective application of solder bumps in an integrated circuit package.  
4            Solder bumps are selectively applied in a solder bump integrated circuit  
5            packaging process so that portions of a circuit can be effectively disabled.  
6            The bumps may be selectively applied either to a die or to the substrate using  
7            multiple solder masks, one for each pattern of solder bumps desired or can be  
8            otherwise applied in multiple patterns depending upon which portions of the  
9            circuitry are to be active and which are to be disabled.  
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